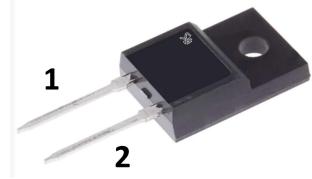
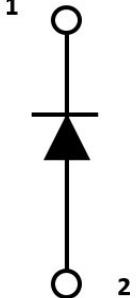


Silicon Carbide Schottky Barrier Diode

1200V, 10A SiC SBD

General Description			
Product Summary			TO-220AC
V _{RRM}	1200	V	
I _F @ T _c =140°C	10	A	
Q _C @ VR=800V	49	nC	
E _c @ VR=800V	25.3	μJ	
Features			Graphic Symbol
<ul style="list-style-type: none"> Temperature independent switching behavior No reverse recovery current / No forward recovery Excellent thermal performances High surge current capability 			
Applications			
<ul style="list-style-type: none"> Solar inverter / Renewable energy applications Uninterruptible power supply Power factor correction Motor drives 			

Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V _{RRM}	1200	V
Continuous Forward Current, D=1	T _c =25°C	31	A
	T _c =140°C	10	
Non-Repetitive Peak Forward Surge Current, Half Sine Wave, 10ms	T _c =25°C	94	A
	T _c =150°C	78	
i ² t Value, 10ms	∫i ² dt	44.1	A
Non-Repetitive Peak Forward Current, 10us	I _{F,max}	564	A
Power Dissipation	P _D	114	W
Storage Temperature Range	T _{STG}	-55 to 150°C	°C
Operating Junction Temperature Range	T _J	-55 to 175°C	°C

Thermal Characteristics

Parameter	Symbol	Conditions	Min.	Typ	Max	Unit
Maximum Junction-to-Ambient ¹	R _{thJA}	TO-220AC	-	0.94	1.32	°C/W
Maximum Junction-to-Case ¹	R _{thJC}	TO-220AC	-	-	60	°C/W

Electrical Characteristics (T_A=25°C unless otherwise noted)

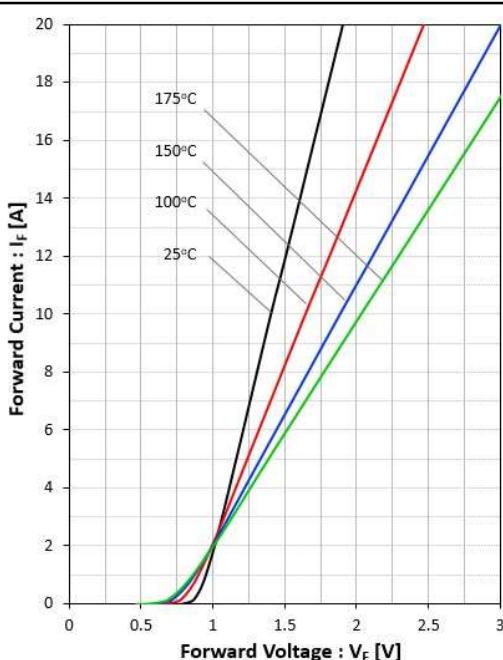
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
STATIC CHARACTERISTICS						
DC Blocking Voltage	V _R	I _R =100uA, T _j =25°C	1200	-	-	V
		I _R =100uA, T _j =175°C	1200	-	-	
Forward Voltage	V _F	I _F =10A, T _j =25°C	-	1.4	1.8	V
		I _F =10A, T _j =150°C	-	1.8	2.2	
		I _F =10A, T _j =175°C	-	2.0	2.4	
Reverse Current	I _R	V _R =1200V, T _j =25°C	-	1.2	60	μA
		V _R =1200V, T _j =150°C	-	15	120	
		V _R =1200V, T _j =175°C	-	25	250	
DYNAMIC CHARACTERISTICS						
Total Capacitive Charge	Q _C	V _R =800V, T _j =25°C $Q_C = \int_0^{V_R} C(V) dV$	-	49	-	nC
Total Capacitance	C	V _R =0.1V, f=1MHz, T _j =25°C	-	810	-	pF
		V _R =400V, f=1MHz, T _j =25°C	-	54.7	-	
		V _R =800V, f=1MHz, T _j =25°C	-	40	-	
Capacitance Stored Energy	E _C	V _R =800V, f=1MHz, T _j =25°C	-	25.3	-	μJ

Notes:

1. Heat sink size: 25 x 17 x 4 cm³
2. Pulse Test: Pulse Width ≤300μs, Duty Cycle≤ 2%.
3. The power dissipation is limited by 175°C junction temperature.
4. The data is theoretically the same as I_F and I_{FSM} in real applications, should be limited by total power dissipation.

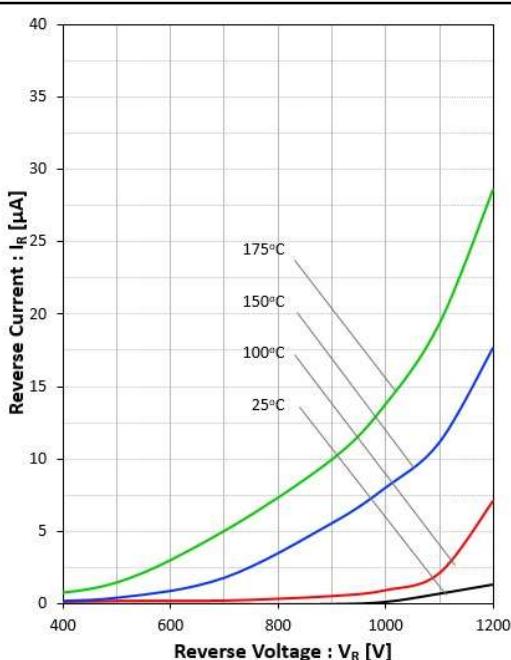
Typical Operating Characteristics

Figure 1: Typical Forward Characteristics



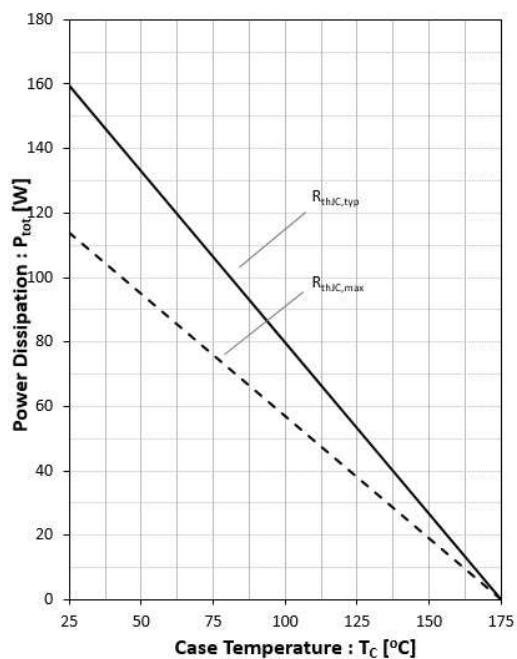
$$I_F = f(V_F, T_j)$$

Figure 2: Typical Reverse Characteristics



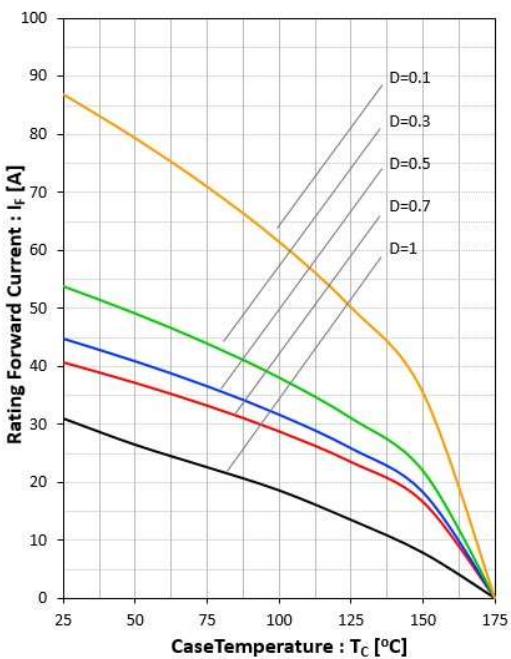
$$I_R = f(V_R, T_j)$$

Figure 3: Power Derating Curves

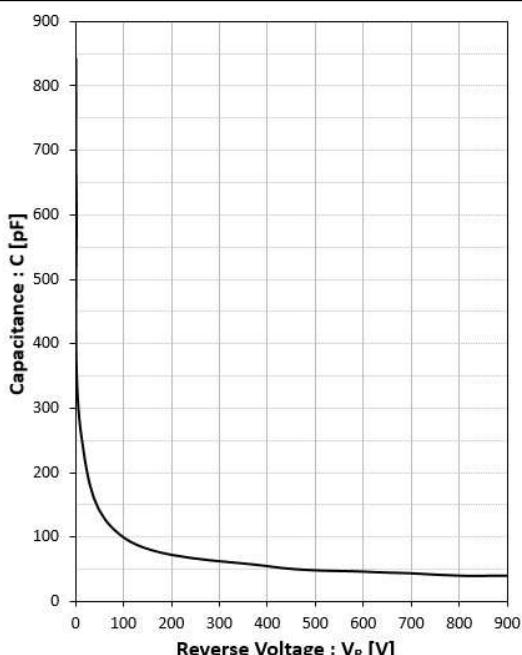
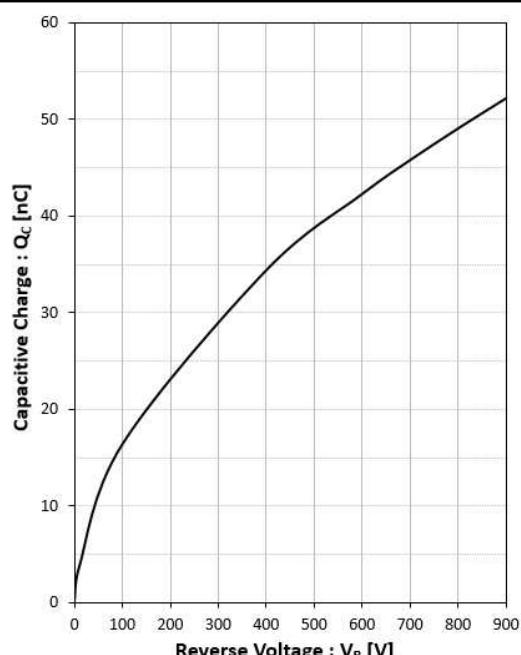
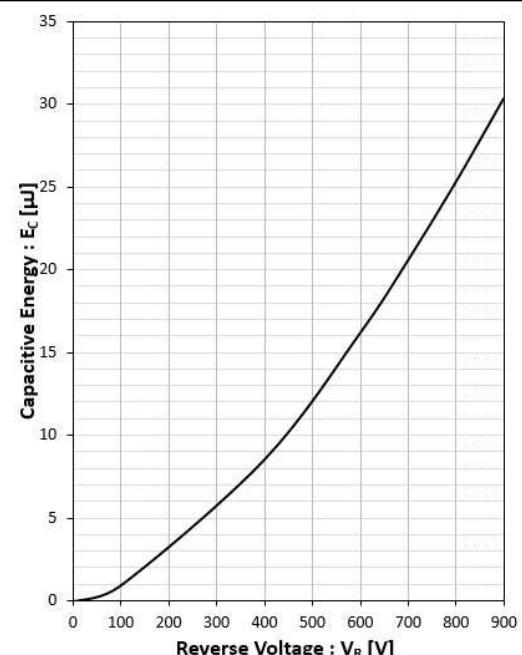
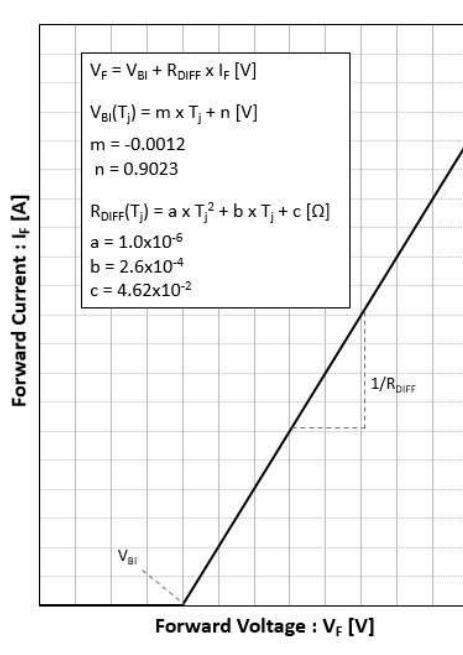


$$P_{tot} = f(T_C); T_j=175^\circ\text{C}$$

Figure 4: Current Derating Curves



$$I_F = f(T_C); R_{thJC,max}; V_{F,max}; T_j \leq 175^\circ\text{C}; D = I_F/T$$

Typical Operating Characteristics (Cont.)
Figure 5: Typical Junction Capacitance

 $C = f(V_R); f=1\text{MHz}$
Figure 6: Typical Capacitive Charge

 $Q_C = f(V_R); f=1\text{MHz}$
Figure 7: Typical Capacitive Energy

 $E_C = f(V_R); f=1\text{MHz}$
Figure 8: Forward Curve Model

 $I_F = f(V_F, T_j)$

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

TO-220AC
